

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
262-253-5900 FAX 262-253-5919

DESCRIPTION:

ResinLab® Armstrong™ A-661 is a two-part room temperature curing adhesive that produces bonds with excellent shear strength and will maintain its performance after long term exposure to temperatures up to 400 °F / 205 °C.

Armstrong A-661 is a smooth, brushable, non-sag, easy to apply paste that cures to handling strength overnight at room temperature. An elevated cure schedule at or above 165 °F (75 °C), for example 10 minutes @ 150 °C, can be used to accelerate final properties.

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TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	Value:	Test Method or Source:
Color	Gray	Visual
Mix Ratio	Part A to Part B	Calculated
By weight	4 to 1	
By volume	2.5 to 1	
Cure Schedule	24 hours @ 25 °C 10 minutes @150 °C	
Viscosity – Part A	640,000 cps @1/s	Rheometer parallel plate 25mm
Viscosity – Part B	11,000 cps @1/s	455300006291
Viscosity - Mixed	185,000 cps @1/s	
Specific Gravity – Part A	1.60	Calculated
Specific Gravity – Part B	0.96	
Specific Gravity - Mixed	1.41	
Pot Life, defined as the time it takes for initial mixed viscosity to double	1 hour, 35 minutes	Rheometer parallel plate 25mm@1/s 455300006291
Work Life	3 hours (100g sample)	Extrapolated from Henkel LDS
Hardness	85 Shore D	455300006287/ASTM D2240
Lap Shear Strength in psi 0.005" bond line Al to Al		Extrapolated from Henkel LDS Cured 10 minutes @ 149 °C
@ 25 °C	3,300	
@ 82 °C	3,460	
@ 149 °C	760	
@ 204 °C	430	
Tensile Properties:		Extrapolated from Henkel LDS Cured 10 minutes @ 149 °C
Strength	2,800 psi	
Bond Strength	5,300 psi	
Elongation	2%	
Operating Temperature Range	-40 to 205 °C**	

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all

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applications operating at that temperature.

INSTRUCTIONS:

1. Bring both components to room temperature prior to mixing.
2. Cartridge format: Mixer should be attached keeping the cartridge vertical and any air pocket purged this way. After the mixer contains material, the mixer tip can be dropped to dispense pre-bleed amount. Attach a new static mixer with each cartridge, then pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Bulk format: weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. Maintain adequate velocity during dispensing to ensure complete mixing.
4. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
5. Clean up uncured resin with suitable organic solvent such as MEK, acetone or other organic solvent.

SHELF LIFE AND STORAGE:

12 months at 25 °C in bulk packages
9 months DOP at 25 °C in C-kit.
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.